

**Minutes of the CE-2.2 Subcommittee Connector and Socket Specifications
6 – 7 October 2008
Salt Lake City, UT**

Facilitator Carl Fritz welcomed everyone, and said that the meeting would be conducted following the published agenda.

1. Approval of the 31 March – 1 April 2008 Minutes

The minutes of the 31 March – 1 April 2008 meeting in Louisville, KY were approved. Moved by Kevin Rickard and seconded by Ralph Antonelli. The motion was unanimously moved and approved.

It is noted that the CE-2.0 committee will simultaneously approve all actions taken by the subcommittee.

2. SPECIFICATIONS BY PROJECT NUMBERS

A. SP-4965, EIA-540B0AE, Detail Land Grid Array (Carl Fritz)

The committee indicated a desire to possibly supersede this standard for new designs by EIA-364-1000 in the future by incorporating the relevant tests from 540B0AB into EIA-364-1000.

Carl Fritz reported that he sent letter (mccwil349) to EIA for SP ballot to reaffirm specification on 2 May 2008.

SP ballot issued 10 June 2008 with a ballot expiration date of 10 August 2008.

Carl reported that EIA had received 6 and 1 abstention by the 10 August ballot expiration date.

It was moved by Don Chambers and seconded by Dave Bouzek to send the standard to EIA for an EDEC ballot to reaffirm. The motion was unanimously approved. It was also unanimously moved and approved that if there are sufficient ballots and no rejections received that the standard be sent to EIA for EDEC ballot and publication as an EIA Standard. In addition the standard should also be submitted to ANSI for publication as an American National Standard.

B. SP-4970, EIA-540DAAA-A, Detail, DIP

At EDEC for approval.

C. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector

At EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

Carl reported that he sent memo (mccwil347) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Max Peel.

Project cancelled per Cecelia Yates at EIA on 13 May 2008. Cecelia indicated that this specification was actually issued as a letter ballot on 24 January 2002 by Tom Peel.

E. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

F. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

Carl reported that he sent memo (mccwil348) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Tom Peel.

Prepared by:

Carl Fritz, Facilitator, CE-2.2